



Material Content Data Sheet



Sales Product Name	TLE9222LC			Issued	24. January 2018			
MA#	MA001472448							
Package	PG-TSON-14-3			Weight*	42.00 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.990	2.36	2.36	23580	23580
leadframe	inorganic material	phosphorus	7723-14-0	0.005	0.01		119	
	non noble metal	zinc	7440-66-6	0.020	0.05		477	
	non noble metal	iron	7439-89-6	0.401	0.95		9537	
wire	non noble metal	copper	7440-50-8	16.263	38.72	39.73	387234	397367
	non noble metal	copper	7440-50-8	0.093	0.22	0.22	2211	2211
	encapsulation	organic material	carbon black	1333-86-4	0.046	0.11		1097
encapsulation	plastics	epoxy resin	-	2.372	5.65		56482	
	inorganic material	silicondioxide	60676-86-0	20.612	49.08	54.84	490792	548371
leadfinish	non noble metal	tin	7440-31-5	0.621	1.48	1.48	14792	14792
plating	noble metal	silver	7440-22-4	0.091	0.22	0.22	2160	2160
glue	plastics	epoxy resin	-	0.121	0.29		2880	
	noble metal	silver	7440-22-4	0.363	0.86	1.15	8639	11519
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com